

IN THE CLAIMS:

Claims 1-15 and 27-30 were previously cancelled herein. Claims 17, and 20-25 have been amended herein. All of the pending claims 16 through 26 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1-15. (Withdrawn)

16. (Previously Presented) A method of packaging at least one semiconductor die in a high density arrangement comprising:
providing a substrate;
providing a flexible interposer including a first surface having a plurality of electrical contacts thereon for electrically connecting at least one semiconductor die to a substrate, a second surface, and a plurality of open vias extending completely through said flexible interposer from said first surface to said second surface;
providing at least one bare unpackaged semiconductor die having a plurality of bond pads on a first surface thereof;
providing a plurality of electrical contacts;
attaching said at least one semiconductor die to said flexible interposer forming an intermediate structure, said interposer being folded around said at least one bare unpackaged semiconductor die, said at least one bare unpackaged semiconductor die being in electrical communication with said substrate through a portion of the plurality of electrical contacts of said flexible interposer by at least a portion of the plurality of electrical contacts filling at least portions of the plurality of vias extending from the first surface of the interposer to the second surface of the interposer contacting a plurality of bond pads on the first surface of the at least one bare unpackaged semiconductor die; and
attaching said intermediate structure to said substrate.

17. (Currently Amended) The method of claim 16, wherein each of said plurality of ~~vias-are~~ is filled with conductive metal.

18. (Previously Presented) The method of claim 16, wherein said second surface surrounds at least three sides of the at least one bare unpackaged semiconductor die around which said interposer is folded.

19. (Previously Presented) The method of claim 16, wherein said second surface of said interposer surrounds at least two sides of the at least one bare unpackaged semiconductor die around which said interposer is folded.

20. (Currently Amended) The method of claim 16, wherein each of said plurality of ~~bond pads-are~~ is in electrical communication with said plurality of electrical contacts through said plurality of vias in the flexible interposer.

21. (Currently Amended) The method of claim 16, wherein said interposer folds around more than two bare unpackaged semiconductor-~~die~~ dice in a serpentine fashion around groups including at most two bare unpackaged semiconductor-~~die~~ dice therein.

22. (Currently Amended) The method of claim 16, further comprising applying electrical contacts to a top surface of a high density semiconductor package to attach the at least one bare unpackaged semiconductor-~~devices~~ die to said package.

23. (Currently Amended) A method of forming a high density semiconductor package comprising:
providing at least one bare unpackaged semiconductor die having a plurality of bond pads on a surface of said ~~at least one bare unpackaged semiconductor die~~; die;
providing an interposer including a first surface having a plurality of electrical contacts, a second surface, and a plurality of open vias extending completely through said interposer from said first surface to said second surface;
providing ~~a~~ the plurality of electrical contacts;
attaching said at least one bare unpackaged semiconductor die to said interposer to form an intermediate packaging structure having at least a portion of the plurality of electrical contacts filling at least portions of the plurality of vias extending from the first surface of the interposer to the second surface of the interposer contacting a plurality of bond pads on the first surface of the at least one bare unpackaged semiconductor die;
providing a substrate;
attaching said substrate to said intermediate structure; and
connecting ~~between~~ said substrate and said at least one bare unpackaged semiconductor die.

24. (Currently Amended) The method of claim 23, wherein said attaching said at least one die further comprises:
attaching multiple bare unpackaged semiconductor ~~die~~ dice in groups of two bare unpackaged semiconductor ~~die~~, dice, said semiconductor ~~die~~ dice having a back-to-back configuration, a back side of one bare unpackaged semiconductor die substantially contacting a back side of another bare unpackaged semiconductor die of a group.

25. (Currently Amended) The method of claim 23, wherein said plurality of electrical contacts and said plurality of bond pads provide electrical communication through said plurality of vias of the flexible interposer.

26. (Original) The method of claim 23, further comprising:
forming electrical contacts on a top surface of said package to attach semiconductor device
components.

27-30. (Withdrawn)